

FEATURES		CAPABILITIES	REMARKS
N° of layers		1-40 Layers *	
Board Materials		FR4 - Normal TG (also halogen free) FR4 - High TG (also halogen free) PTFE laminates Ceramic particle filled laminates Aluminium Hybrid laminating	there is a wide range of different types of laminate/prepreg materials from different suppliers
PCB Buildings Technology		Blind&Buried Vias, Backplane, HDI, High Multi-Layer, Backdrill, Heavy Copper Power Pcb/ Metal Substrate, Copper or Resin Filling, Impedance controlled	RIGID-FLEX and FLEX Building technology
Maximum Finished PCB size	Single layer & Double layer	584.2 x 889 mm (23x35")	
	Multilayer	571.5 x 851 mm (22.5x33.5")	
	Backplane technology	571.5 x 1143 mm (22.5x45") *	
PCB thickness	Single layer - 2 layers	0.20 - 7.00 mm (8 - 275.6 mil)	H.A.L 0.60 - 4.00 mm (23.6 - 157.5 mil); ENIG 0.20 - 7.00 mm (8 - 275.6 mil); Immersion Tin/Silver 0.40 - 5.00 mm (15.7 - 196.9 mil); Hard Gold 0.20 - 5.00 mm (8 - 196.9 mil)
	Multilayers	0.40 - 7.00 mm (15.7 - 275.6 mil)	
	Tolerance	≤ 1.00 mm: ± 0.1 mm (≤ 40 mil: ± 4 mil) ≥ 1.00 mm: ± 10 % (≥ 40 mil)	
Base Copper thickness		1/3 Oz, 1/2 Oz, 1 to 10 Oz	1 Oz = 35 µm
Surface Finish		H.A.L lead free (RoHS - Pb free), H.A.L. with Pb, Immersion gold or ENIG (RoHS) Immersion Tin, Immersion Silver, Hard Gold, ENEPIG, Peelable solder mask Hybrid Surface finish	
Solder Mask	Colors	Green matte/glossy, Yellow, Black, Blue, Red, White, Purple	
	Minimum width	 <p>Base Copper ≤ 1 Oz (35 µm): 0.1 mm (4 mil) for Green, 0.13 mm (5 mil) other colors Base Copper 2 Oz (70 µm) - 4 Oz (140 µm): 0.15 mm (6 mil)</p>	Minimum 0.2 mm (8 mil) between copper areas
Silkscreen	Colors	White, Yellow, Black	
Finished Mechanical Hole Size PTH		0.1 - 6.2 mm (4 - 244 mil)	
Laser Drilling Size		0.1 - 0.15 mm (4 - 6 mil) *	
HDI		4 + N + 4 *	
Aspect Ratio (Mechanical THT)		12:1	20:1 for Hole diameter > 0.20 mm (8 mil)
Minimum Track Width/Space		76 - 76 µm (3 / 3 mil) on internal layers *	Using copper thickness 1/3 Oz (12 µm), 1/2 Oz (17.5 µm)
		76 - 76 µm (3 / 3 mil) on external layers *	Using copper thickness 1/3 Oz (12 µm)
Minimum Pad Size for Mechanical Drillings		0.4 mm (16 mil) *	Using copper thickness ≤ 1/2 Oz (17.5 µm) and 0.2 mm (8 mil) drilling size
Other Special Processes		Impedance Control (tolerance: ± 10 %) Blind&Buried Vias Filled holes Pressfit holes (tolerance: ± 50 µm (± 2 mil)) Z-axis routing Gold Finger Counter bore and Counter sink Chamfering/Beveling	on special products also ± 5 %

* Different solutions are available on demand